

COVER FILM AND ELECTRONIC COMPONENT PACKAGE USING SAME

ABSTRACT

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[Problem] To provide: a cover film with excellent interlayer adhesiveness without using an anchor coating agent; and an electronic component package using the same.

[Solution] Provided is a cover film having at least a substrate layer and a sealant resin layer, wherein the sealant resin layer is formed to contact one surface of the substrate layer or is formed on an intermediate resin layer contacting one surface of the substrate layer, and the sealant resin layer contacting the substrate layer or the intermediate resin layer contacting the substrate layer contains an epoxidized fatty acid or a derivative thereof. The epoxidized fatty acid or a derivative thereof in the sealant resin layer contacting the substrate layer or in the intermediate resin layer contacting the substrate layer is preferably at a content of 0.5 parts by mass or less with respect to 100 parts by mass of a resin component constituting the intermediate resin layer contacting the substrate layer and/or the sealant resin layer contacting the substrate layer.

Figure 1

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